

Title (en)

PARTICLE BOARD WITH A HIGH DEGREE OF FLEXURAL RESISTANCE AND A HIGH BEND-ELASTICITY MODULUS

Title (de)

HOLZSPANPLATTE MIT HOHER BIEGEFESTIGKEIT UND HOHEM BIEGE-E-MODUL

Title (fr)

PANNEAU DE PARTICULES A RESISTANCE ET COEFFICIENT D'ELASTICITE A LA FLEXION ELEVES

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Application

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Abstract (en)

[origin: WO9932285A1] The invention relates to a particle board (1) with a high degree of flexural resistance and a high bend-elasticity modulus, consisting of one or more layers (2, 3, 5, 6) of wood chips, said wood chips having been impregnated with condensation resins and compacted under pressure, at a high temperature. The size of the chips may vary. According to the invention, a woven, bonded or non-woven fabric (5) consisting of natural fibres is arranged inside or between the individual layers of glued wood chips.

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